MBR0530

Schottky Rectifier

Features

- 0.5 A, Low Forward Voltage less than 430 mV
- Compact Surface Mount Package with The Same Footprint as Mini-melf

Applications

- Solid-State Relays
- Industrial Controls
- Lighting Controls
- Static Power Switches
- AC Motor Starters

ABSOLUTE MAXIMUM RATINGS (T_A = 25°C unless otherwise noted)

Symbol	Description	Value	Unit
V_{RRM}	Maximum Repetitive Reverse Voltage	30	>
I _{F(AV)}	Average Rectified Forward Current	500	mA
I _{FSM}	Non Repetitive Peak Forward Current (Surge Applied at Rated Load Conditions Half–Wave, Single–Phase, 60 Hz)	5.5	А
T _{STG}	Storage Temperature Range	-65 to +150	°C
T _{Jmax}	Operating Junction Temperature	-65 to +125	°C

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

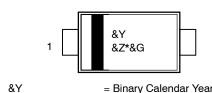
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SOD-123 CASE 425-04

MARKING DIAGRAM



= Binary Calendar Year Coding Scheme

&Z = Assembly Plant Code = Specific Device Code

&G = Single Digit Weekly Datecode

Table 1. ORDERING INFORMATION

Part Number	Top Mark	Package	Packing Method
MBR0530	B3	SOD-123 2L	Tape and Reel

Table 2. THERMAL CHARACTERISTICS (Values are at T_A = 25°C unless otherwise noted)

Symbol	Parameter	Value	Unit
$R_{ hetaJA}$	Thermal Resistance, Junction-to-Ambient (Note 1)	206	°C/W
$R_{ hetaJL}$	Thermal Resistance, Junction-to-Lead	173	°C/W

^{1. 1} inch square pad size on FR-4 board.

MBR0530

Table 3. ELECTRICAL CHARACTERISTICS (Values are at $T_A = 25$ °C unless otherwise noted)

Symbol	Parameter	Conditions	Min.	Max.	Unit
V _F		I _F = 100 mA		375	mV
	Forward Voltage	I _F = 100 mA, T _A = 100°C		340	
		I _F = 500 mA		430	
		I _F = 500 mA, T _A = 100°C		420	
	Reverse Current	V _R = 15 V		20	μΑ
I _R		V _R = 30 V		130	μΑ
		V _R = 30 V, T _A = 100°C		5	mA

TYPICAL PERFORMANCE CHARACTERISTICS

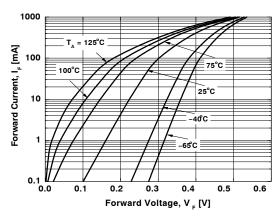


Figure 1. Forward Current vs. Forward Voltage

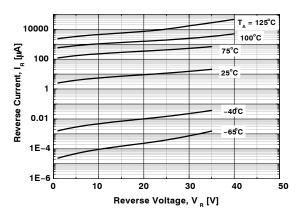


Figure 2. Reverse Current vs. Reverse Voltage

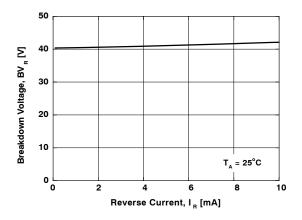


Figure 3. Breakdown Voltage vs. Reverse Current

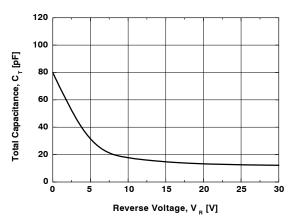
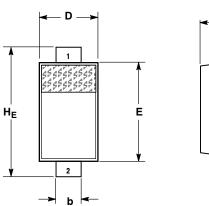


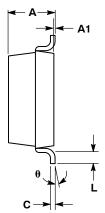
Figure 4. Total Capacitance



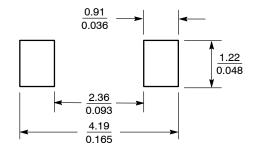
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DATE 07 OCT 2009





SOLDERING FOOTPRINT*



SCALE 10:1

- NOTES:
 1. DIMENSIONING AND TOLERANCING PER ANSI
- Y14.5M, 1982. 2. CONTROLLING DIMENSION: INCH.

	MILLIMETERS			INCHES		
DIM	MIN	NOM	MAX	MIN	NOM	MAX
Α	0.94	1.17	1.35	0.037	0.046	0.053
A1	0.00	0.05	0.10	0.000	0.002	0.004
b	0.51	0.61	0.71	0.020	0.024	0.028
C			0.15			0.006
D	1.40	1.60	1.80	0.055	0.063	0.071
Е	2.54	2.69	2.84	0.100	0.106	0.112
HE	3.56	3.68	3.86	0.140	0.145	0.152
L	0.25			0.010		-
θ	0°		10°	0°		10°

GENERIC MARKING DIAGRAM*



XXX = Specific Device Code

= Date Code

= Pb-Free Package

(Note: Microdot may be in either location)

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot " •", may or may not be present.

STYLE 1: PIN 1. CATHODE 2. ANODE

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DESCRIPTION:	SOD-123		PAGE 1 OF 1	

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^{*}For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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